



**Alfa-MOS  
Technology**

**AFN3416  
20V N-Channel  
Enhancement Mode MOSFET**

## General Description

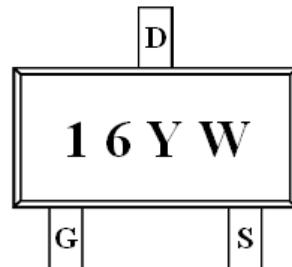
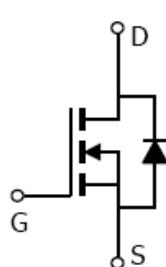
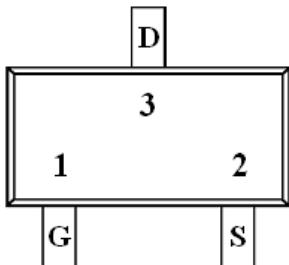
AFN3416, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- $I_D = 4.0A, R_{DS(ON)}=26m\Omega @ V_{GS}=4.5V$
- $I_D = 3.2A, R_{DS(ON)}=30m\Omega @ V_{GS}=2.5V$
- $I_D = 2.8A, R_{DS(ON)}=36m\Omega @ V_{GS}=1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design

## Pin Description ( SOT-23-3L )



## Application

- Portable Equipment
- Battery Powered System
- Net Working System

## Pin Define

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN3416S23RG	16YW	SOT-23-3L	Tape & Reel	3000 EA

- ※ 16 parts code
- ※ Y year code ( 0 ~ 9 )
- ※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )
- ※ AFN3416S23RG : 7" Tape & Reel ; Pb-Free ; Halogen-Free



### Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	20	V
Gate –Source Voltage	$V_{GSS}$	$\pm 12$	V
Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$I_D$	4.0	A
		3.2	
Pulsed Drain Current	$I_{DM}$	10	A
Continuous Source Current(Diode Conduction)	$I_S$	1.6	A
Power Dissipation	$P_D$	1.25	W
		0.8	
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	120	$^\circ\text{C}/\text{W}$

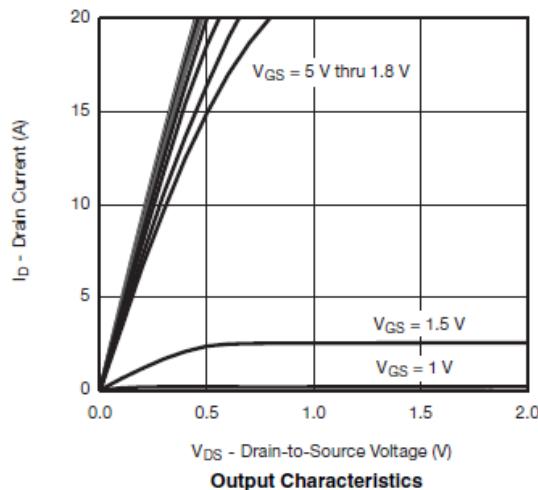
### Electrical Characteristics

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

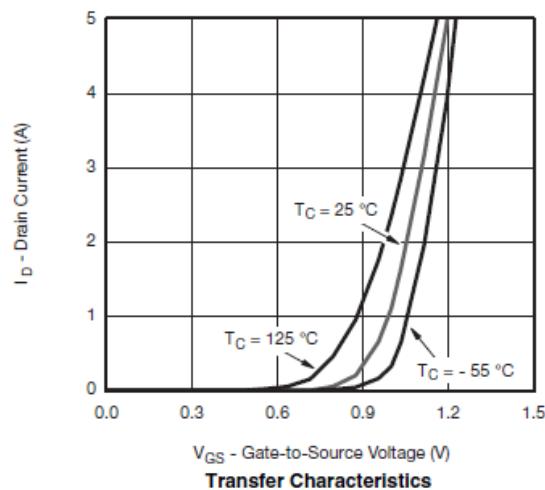
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.4		1.0	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$			1	uA
		$V_{DS}=16\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5\text{V}, V_{GS}=4.5\text{V}$	6			A
		$V_{DS} \geq 5\text{V}, V_{GS}=2.5\text{V}$	4			
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{V}, I_D=4.0\text{A}$		23	26	m $\Omega$
		$V_{GS}=2.5\text{V}, I_D=3.2\text{A}$		27	30	
		$V_{GS}=1.8\text{V}, I_D=2.8\text{A}$		30	36	
Forward Transconductance	$g_{FS}$	$V_{DS}=10\text{V}, I_D=5.0\text{A}$		35		S
Diode Forward Voltage	$V_{SD}$	$I_S=1.5\text{A}, V_{GS}=0\text{V}$		0.85	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}$ $I_D=3.6\text{A}$		13	19	nC
Gate-Source Charge	$Q_{gs}$			2.8		
Gate-Drain Charge	$Q_{gd}$			2.0		
Input Capacitance	$C_{iss}$	$V_{DS}=10\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		1050		pF
Output Capacitance	$C_{oss}$			235		
Reverse Transfer Capacitance	$C_{rss}$			115		
Turn-On Time	$t_{d(on)}$	$V_{DD}=10\text{V}, R_L=5.5\Omega$ $I_D=3.6\text{A}, V_{GEN}=4.5\text{V}$ $R_G=6\Omega$		10	20	ns
	$t_r$			10	20	
Turn-Off Time	$t_{d(off)}$			25	40	
	$t_f$			10	20	



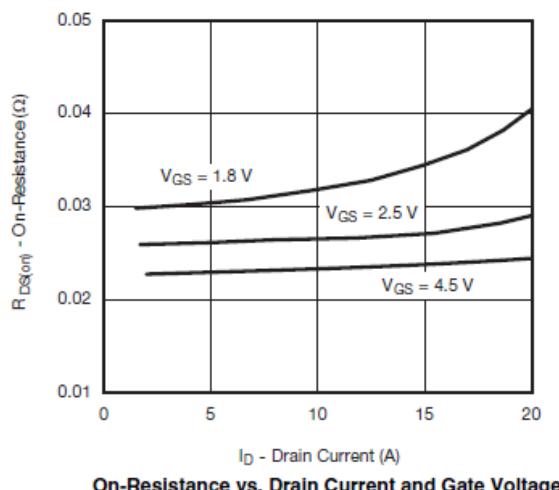
## Typical Characteristics



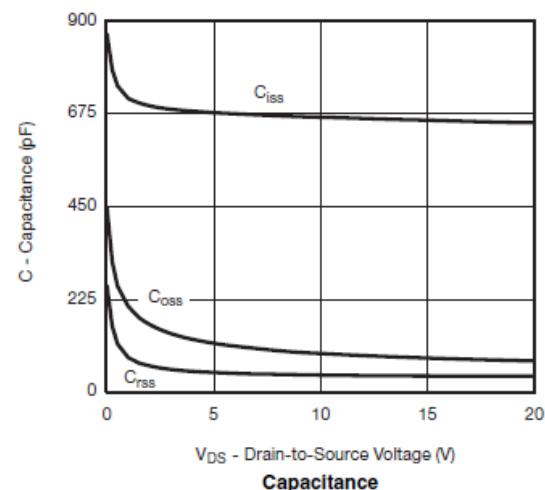
Output Characteristics



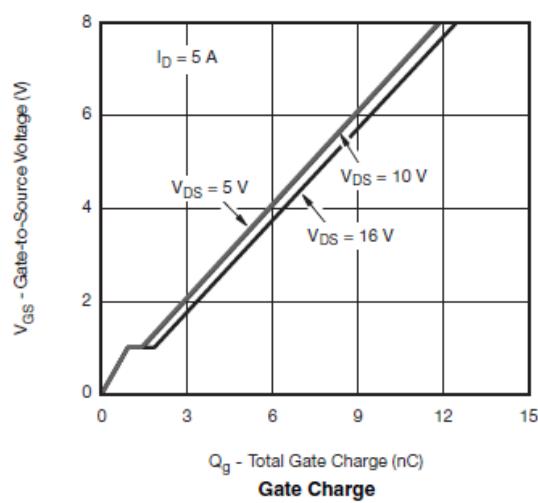
Transfer Characteristics



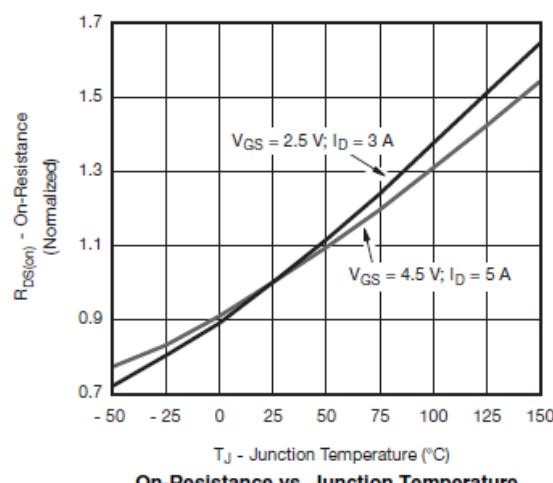
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge



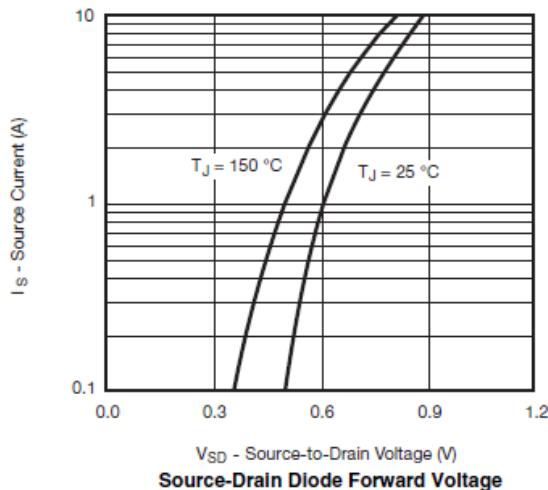
On-Resistance vs. Junction Temperature



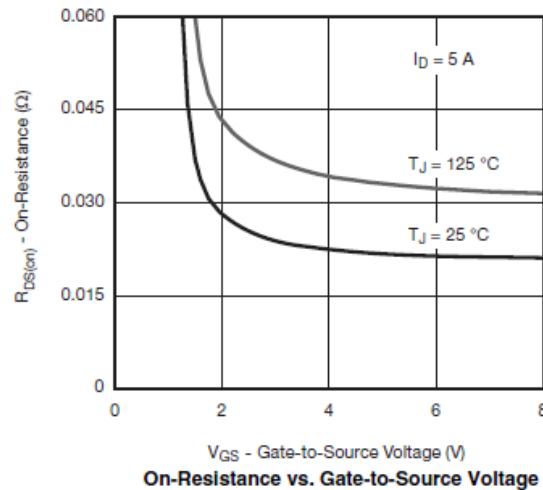
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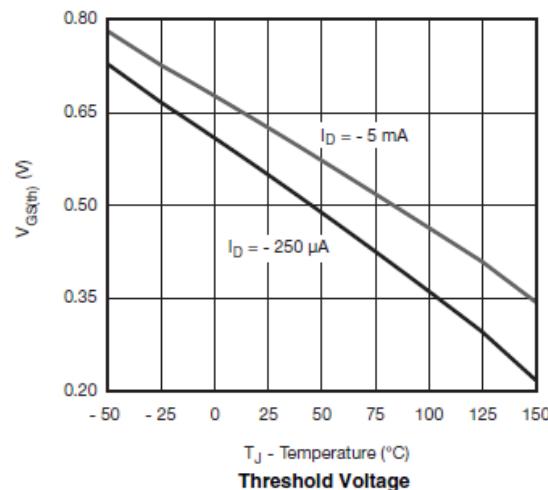
### Typical Characteristics



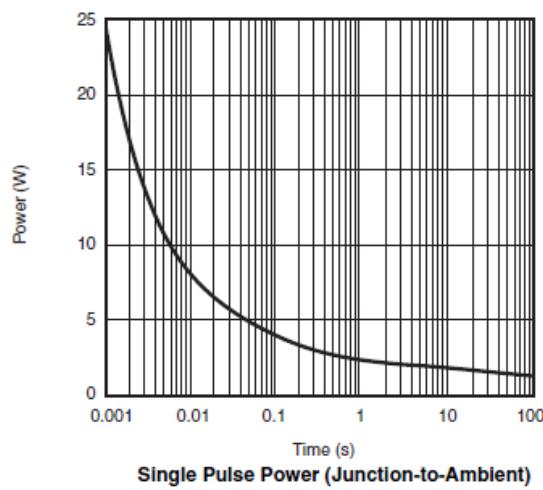
Source-Drain Diode Forward Voltage



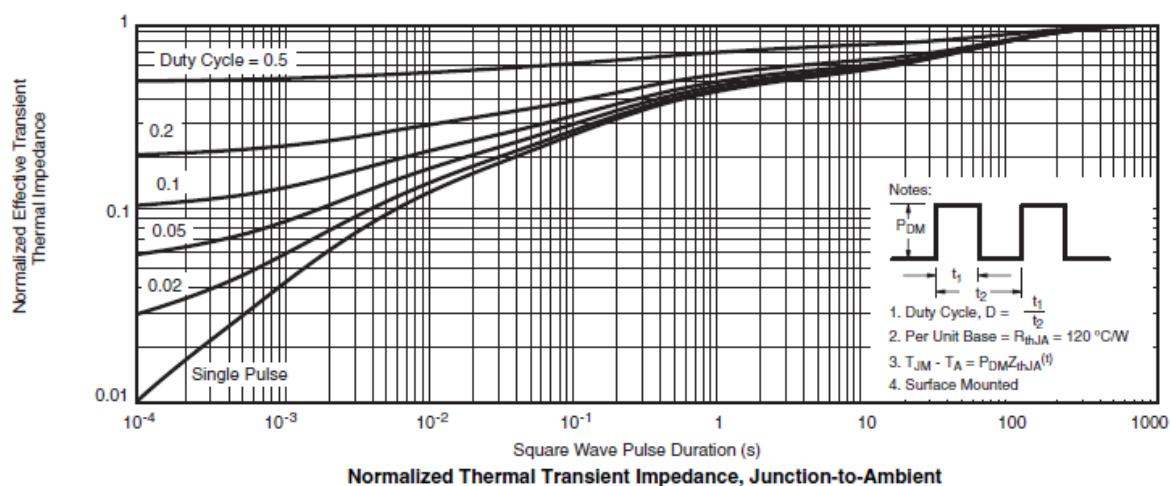
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



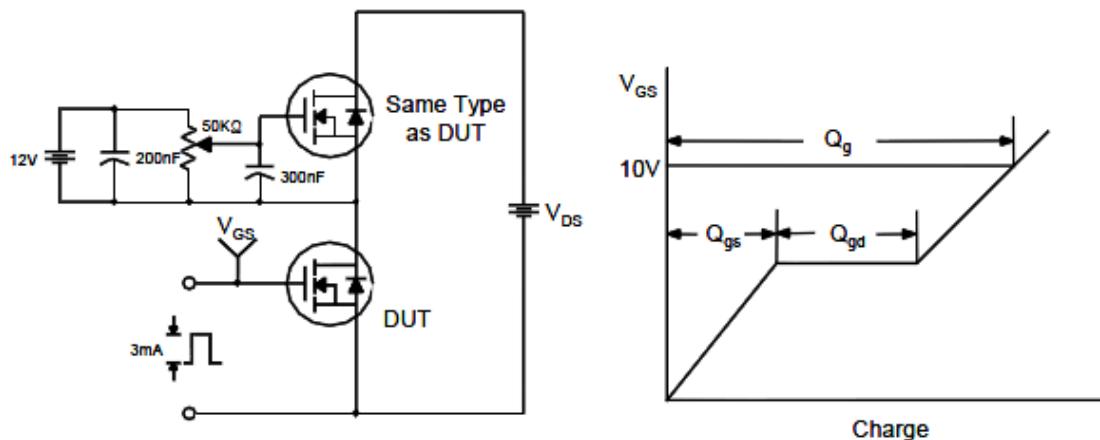
Single Pulse Power (Junction-to-Ambient)



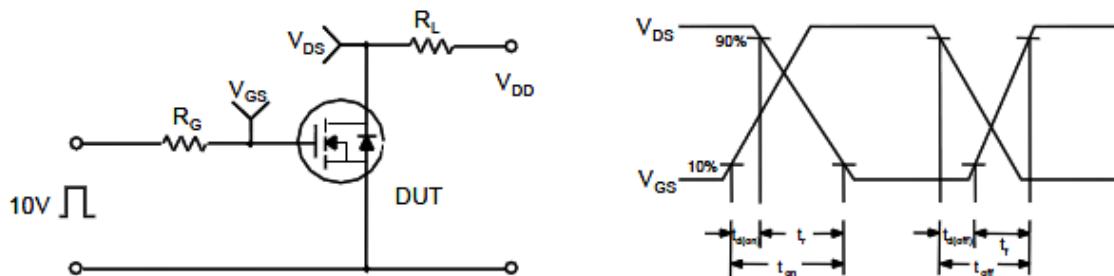


## Typical Characteristics

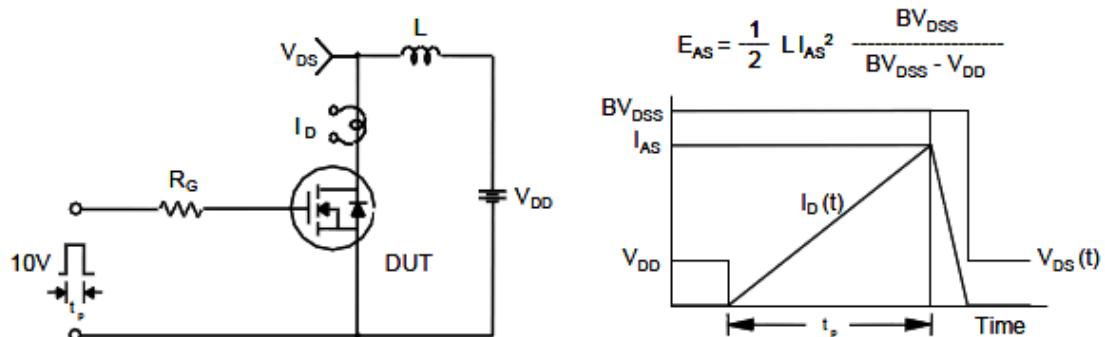
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

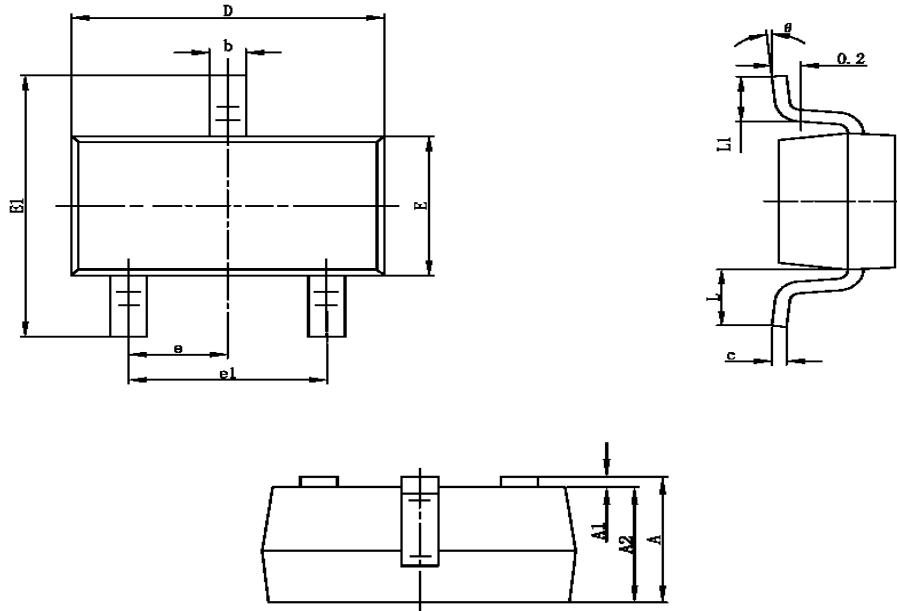




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**Package Information ( SOT-23-3L )**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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